



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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**Raychem**

Specification  
This Issue:  
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Replaces:

**RT-1050/1**  
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Issue 1

**THERMOFIT® ADHESIVE AND SEALANT  
THERMOFIT S-1017**

Thermofit S-1017 thermoplastic adhesive was developed for use with Thermofit heat-shrinkable products where the molded part or tubing is precoated with adhesive on the bonding area. This adhesive is tough and flexible and bonds to polyolefins, vinyls, neoprene, lead, and many other metals such as steel and aluminum.

PROPERTY	UNIT	REQUIREMENT	METHOD OF TEST
<b>PHYSICAL</b>			
Visual		Pass	Section 4.3.1.1
Specific Gravity		0.95 ± .05	Section 4.3.1.2 ASTM D 792
Viscosity, at 191° C	centipose	9000 ± 3000	Section 4.3.1.3.2 ASTM D 1084 Method B
Softening Point	C	120 ± 10	E28
Low Temperature Impact	C	-20 max	4.3.1.7, ASTM D 746
Brittleness			
Blocking (Cohesive @ 55° C)		Pass	4.3.1.8 ASTM D 1146
Adhesive Peel*	Pounds/inch width		Section 4.3.1.9
Polyethylene		20 minimum	
Lead		5 minimum	
Neoprene		10 minimum	
PVC		30 minimum	
Steel		15 minimum	
<b>CHEMICAL</b>			
Water Absorption	Percent	1.0 maximum	Section 4.3.2.1 ASTM D 570
Corrosive Effect		Pass	Section 4.3.2.2 ASTM D 2671
16 hours at 121° C (250° F)			Method B
Environmental Stress-Cracking		Pass	Section 4.3.2.3 ASTM D 1693
48 hours at 50° C			
Environmental Stress-Cracking		Pass	Section 4.3.2.4 ASTM D 1693
of Substrate			
30 days at 50° C			
Fungus Resistance		Rating of 1 or less	Section 4.3.2.5 ASTM G 21

Solvent and Fluid Resistance Weight change after 24 hours at 23° C (74° F): Detergent Solution (#12) Hydraulic Fluid (MIL-H-5606) Lube Oil (Mil-L-7808) ASTM Oil (#49)	Percent	3 maximum 10 maximum  5 maximum 15 maximum	Section 4.3.2.6 ASTM D 543
ELECTRICAL Volume Resistivity	ohm-cm	10 <sup>10</sup> min	Section 4.3.3.1 ASTM D 257
Dielectric Strength	volts/mil	500 min	Section 4.3.3.2 ASTM D 149

Molding temperature for 4.2.1.1 shall be 149° C (300 °F).

Acceptance Tests: Visual, Viscosity, Peel (Steel)